

Product/process change notification

PCN N° 2023-270-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

Implementation of new mold compound and additional assembly and final test location at Tongfu Tongke (Nantong) Microelectronics Co., Ltd. (TFTK) for products in TO247-3 package

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2024-01-26
- Infineon aligns with the widely recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG

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Management Board Jochen Hanebeck (CEO), Elke Reichart, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg Registered office Neubiberg Commercial register Amtsgericht München HRB 126492



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Products affected

Please refer to attached affected product list "pcn_2023-270-A_[customer-no].pdf"

Detailed change information

Subject

Implementation of a new mold compound.

Introduction of an additional BE assembly location.

Reason

Discontinuation of currently used mold compound by supplier and capacity extension.

Description	Old	New	
Mold compound	■ Kyocera KE G300 BH	■ Sumitomo EME E500 HA	
Assembly and final test site	 ATX Semiconductor (Weihai) Co. Ltd. 	 ATX Semiconductor (Weihai) Co. Ltd. or Tongfu Tongke (Nantong) Microelectronics Co., Ltd. (TFTK) 	

Product identification

Traceability assured via lot code.

Impact of change

No impact on electrical performance. Quality and reliability verified by qualification. There is no change in form, fit and function.

Attachments

"pcn_2023-270-A_[customer-no].pdf" 2_cip23270_a.pdf

affected product list qualification report



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▶ Time schedule

Final qualification report available
 First samples available on request
 Intended start of delivery 2024-03-15 or earlier on specific customer request

If you have any questions, please do not hesitate to contact your local sales office.

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Affected products sold to DIGI-KEY, THIEF RIVER FALLS, USA (4002348)

Sales name	SP number	OPN	Package	Customer part number
IHW20N135R5	SP001078568	IHW20N135R5XKSA1	PG-TO247-3	IHW20N135R5XKSA1
IHW30N135R5	SP001607186	IHW30N135R5XKSA1	PG-TO247-3	IHW30N135R5XKSA1
IHW30N65R6	SP005399486	IHW30N65R6XKSA1	PG-TO247-3	IHW30N65R6XKSA1
IHW40N135R5	SP001607192	IHW40N135R5XKSA1	PG-TO247-3	IHW40N135R5XKSA1
IHW40N65R6	SP005399488	IHW40N65R6XKSA1	PG-TO247-3	IHW40N65R6XKSA1
IHW50N65R6	SP005399490	IHW50N65R6XKSA1	PG-TO247-3	IHW50N65R6XKSA1
IKW08N120CS7	SP005419704	IKW08N120CS7XKSA1	PG-TO247-3	IKW08N120CS7XKSA1
IKW15N120CS7	SP005419706	IKW15N120CS7XKSA1	PG-TO247-3	IKW15N120CS7XKSA1
IKW25N120CS7	SP005419560	IKW25N120CS7XKSA1	PG-TO247-3	IKW25N120CS7XKSA1
IKW40N120CS7	SP005415716	IKW40N120CS7XKSA1	PG-TO247-3	IKW40N120CS7XKSA1
IKW50N120CS7	SP005419710	IKW50N120CS7XKSA1	PG-TO247-3	IKW50N120CS7XKSA1